

	PRODUCT SPECIFICATION	FCI ジャパン
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COMPACT FLASH CARD HEADER

1. Objective

This specification covers the standard performance and evaluating conditions of COMPACT FLASH CARD HEADER.

(This product shall meet requirements of CF specification Rev.1.4)

2. Scope

2.1 Header : 62453-022

2.2 Header with eject mechanism : 62451-022L

3. Materials and Surface Finish

Materials and Surface Finish are referred to the product drawings.

4. Performance

4.1 Rating Current : AC/DC 0.5A MAX.per Contact

4.2 Rating Voltage : AC/DC 500V

4.3 Temperature Rise : Max 30°C

4.4 Operating Temperature Range : -20°C ~ +60°C

4.5 Storage Temperature Range : -40°C ~ +70°C

Unless otherwise specified, the performance of connectors given in the attached list shall satisfy the values specified in Table 4.1~4.3, under the environmental conditions (JIS C0010) listed below.

When 68pos.socket connector to be used for the test, it should meet the requirements of PC Card Standard.

- Temperature : 15 to 35°C
- Relative humidity : 25 to 85%
- Atmospheric pressure : 86 to 106 KPa

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Table 4.1 Electrical Specification

No.	Item	Requirement	Test Condition	Applicable #1 classification	
				E	H
1	Contact Resistance (Low level)	Initial : 40mΩ MAX. After test : 20mΩ MAX.	EIA-364-23A Open circuit voltage:20mV MAX. Test current : 1mA		○
2	Insulation Resistance	Initial : 1000MΩ MIN. After test : 100MΩ MIN.	EIA-364-21A Apply DC 500V 1min.		○
3	Dielectric Withstanding Voltage	No arc-over or insulation breakdown. Current leakage : 1mA MAX.	EIA-364-20A AC 500Vrms 1min.		○

Table 4.2 Mechanical Specification

1	Single Pin Holding Force	1kgf(9.8N) MIN.	EIA-364-29A ·Push out speed 25mm/min.		○
2	Total Mating Force	3kgf(28.8N) MAX.	EIA-364-13A ·Suitable CF Card to be used. ·Mating/unmating speed : 25mm/min.	○	○
3	Total Unmating Force	0.5kgf(4.9N) MIN. 2.5kgf(24.5N) MAX.	EIA-364-13A ·Suitable CF Card to be used. ·Mating/unmating speed : 25mm/min.	○	○
4	Durability	No physical or mechanical damage which affects connector function After test Contact resistance change from initial value : 20mΩ MAX.	EIA-364-09B ·Suitable CF Card to be used. ·10,000 cycles ·400-600 cycles per hour. ·Ejection to be done by eject mechanism	○	○

*1 E : Eject mechanism
H : 50pos. pin header

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Table 4.3 Environmental Resistance Specification

No.	Item	Requirement	Test Condition	Applicable #1 classification	
				E	H
1	Shock	No physical or mechanical damage or disassociation of parts. No discontinuity greater than 100 nanoseconds.	EIA-364-27A Test condition A 50G, 11msec. Semi-Sine wave	○	○
2	Vibration	No physical or mechanical damage or disassociation of parts. No discontinuity greater than 100 nanoseconds.	EIA-364-28A Test condition III 15G, 10-2000 Hz	○	○
3	Humidity	After test ·Contact resistance change from initial value : 20mΩ MAX. ·Insulation resistance : 100MΩ MIN.	·EIA-364-31A ·Method III ·10 cycles ·80 to 95%RH ·25~+65°C ·With CF card mated		○
4	Thermal Shock	After test ·Contact resistance change from initial value : 20mΩ MAX. ·Insulation resistance : 100MΩ MIN.	·EIA-364-32B test condition A ·-55°C to +85°C ·5 cycles (1 hour/1 cycle) ·With CF card mated		○
5	Mixed Flowing Gas	After test ·Contact resistance change from initial value : 20mΩ MAX. ·Insulation resistance : 100MΩ MIN.	·EIA-364-65 Class II ·30°C, 70%RH Cl ₂ 10ppb NO ₂ 200ppb H ₂ S 10ppb ·96 hours ·With CF card unmated		○

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Table 4.3 Environmental Resistance Specification

No.	Item	Requirement	Test Condition	Applicable *1 classification	
				E	H
6	Resistance To Solder Heater	No physical or mechanical damage or disassociation of parts.	·Pre-Heat Temperature :100~150°C ·Pre-Heat Duration :60 sec MIN. ·Soldering Temperature : 210~240°C ·Soldering Duration : 30 sec MAX.	○	○

*1 E : Eject mechanism
 H : 50pos. pin header

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Table. 1 Test Sequence

	Test Description	Test Group											
		1	2	3	4	5	6	7	8	9	10	11	12
1	Contact Resistance						① ③	① ③	① ③	① ③	① ③	① ③	
2	Insulation Resistance	①								④	④	④	
3	Dielectric Withstanding Voltage		①										
4	Single Pin Holding Force			①									
5	Total Mating Force				①								
6	Total Unmating Force					①							
7	Durability						②						
8	Shock							②					
9	Vibration								②				
10	Humidity									②			
11	Thermal Shock										②		
12	Mixed Flowing Gas											②	
13	Resistance to Solder Heat												①

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